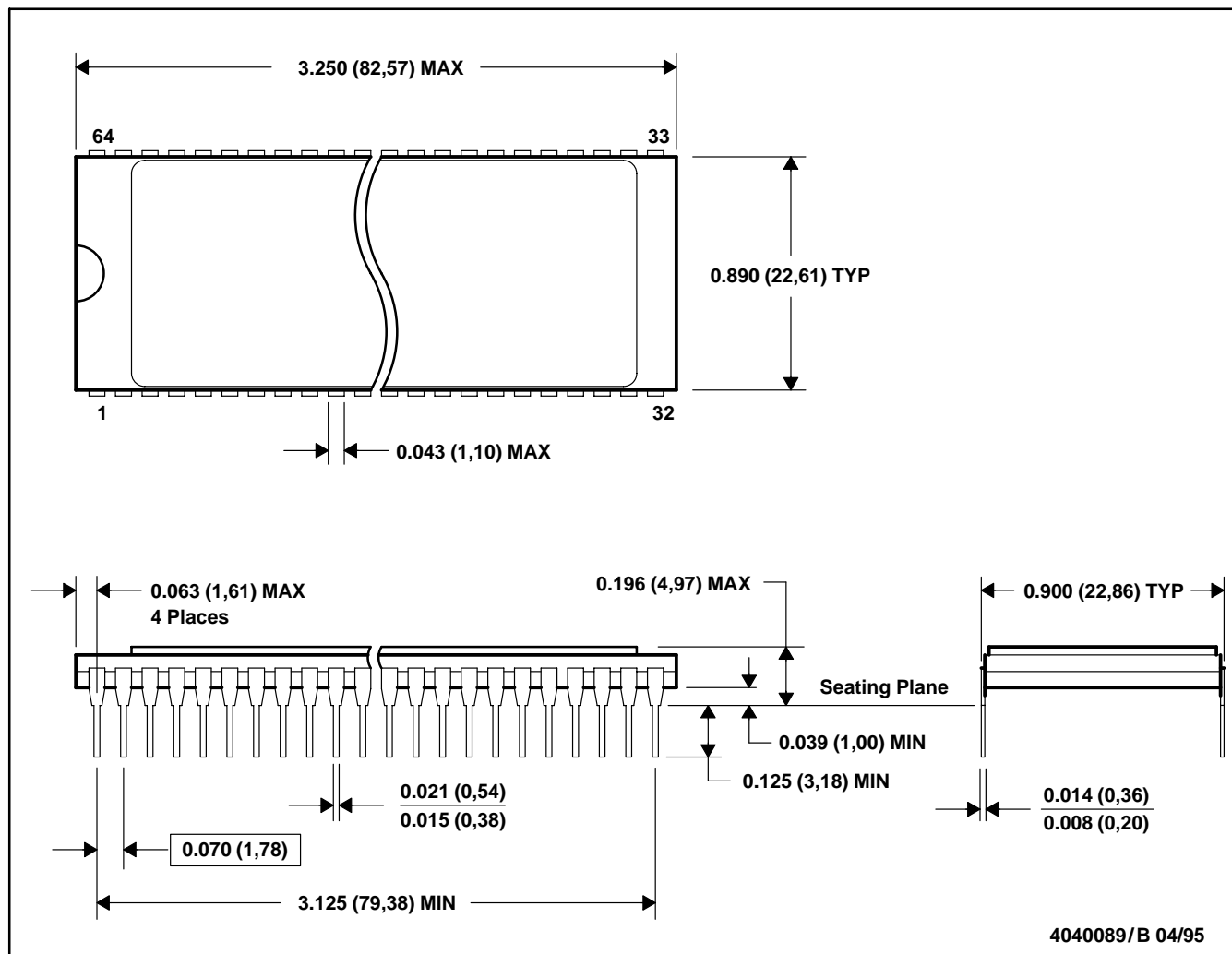


JD (R-CDIP-T64)

CERAMIC SIDE-BRAZE DUAL-IN-LINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

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